



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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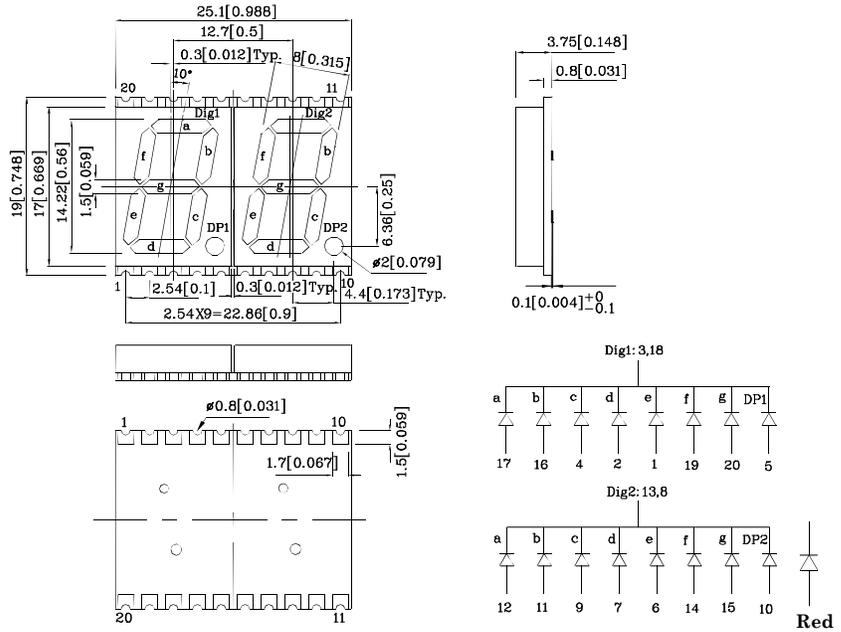


Features

- 0.56 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 200pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS Compliant



Package Schematics



Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.

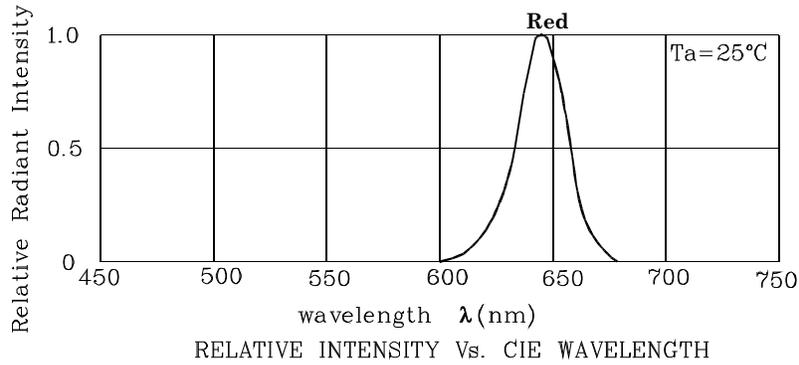
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		Red (AlGaInP)	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	185	mA
Power Dissipation	P_D	75	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

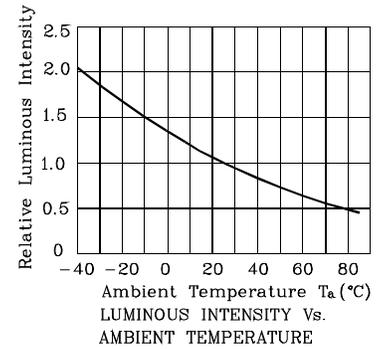
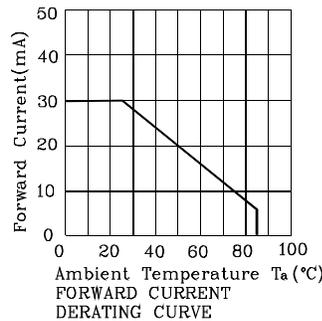
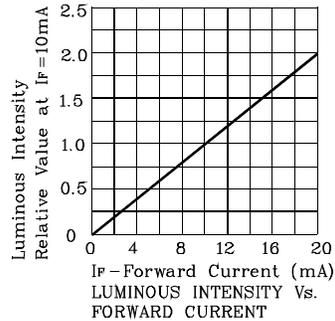
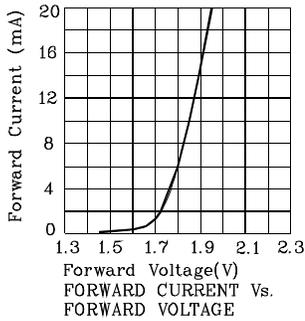
Operating Characteristics ($T_A=25^\circ\text{C}$)		Red (AlGaInP)	Unit
Forward Voltage (Typ.) ($I_F=10\text{mA}$)	V_F	1.85	V
Forward Voltage (Max.) ($I_F=10\text{mA}$)	V_F	2.5	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) ($I_F=10\text{mA}$)	λ_P	645*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) ($I_F=10\text{mA}$)	λ_D	630*	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=10\text{mA}$)	$\Delta\lambda$	28	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	35	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* ($I_F=10\text{mA}$) ucd		Wavelength CIE127-2007* nm λ_P	Description
			min.	typ.		
XZFMDK14C2	Red	AlGaInP	31000 14000*	79990 28990*	645*	Common Cathode, Rt. Hand Decimal

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

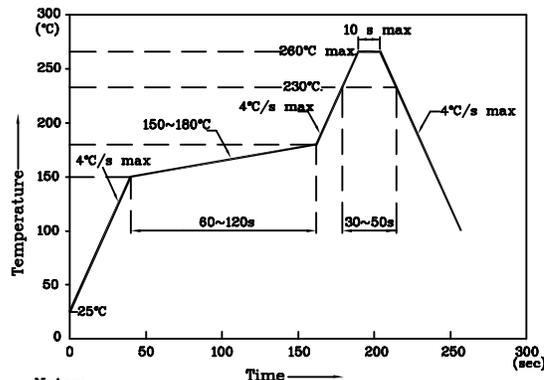


❖ Red



LED is recommended for reflow soldering and soldering profile is shown below.

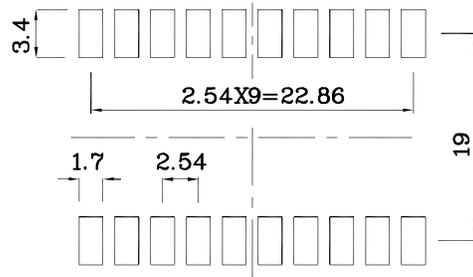
Reflow Soldering Profile for SMD Products (Pb-Free Components)



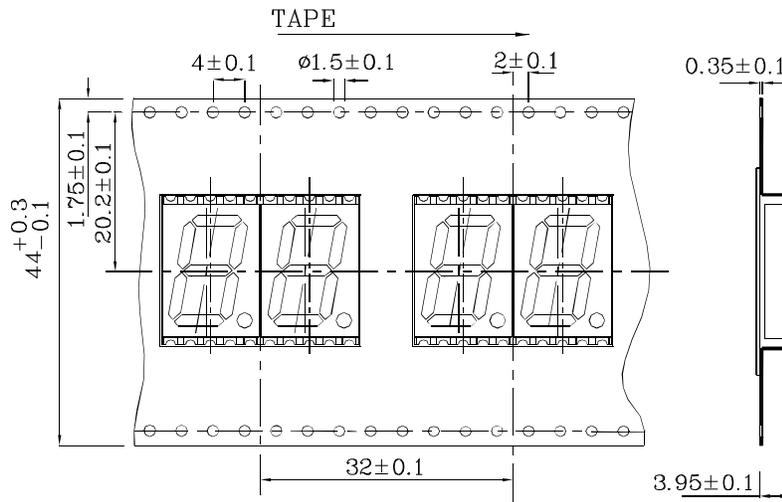
- Notes:
1. Maximum soldering temperature should not exceed 280°C
 2. Recommended reflow temperature: 145°C-260°C
 3. Do not put stress to the epoxy resin during high temperatures conditions



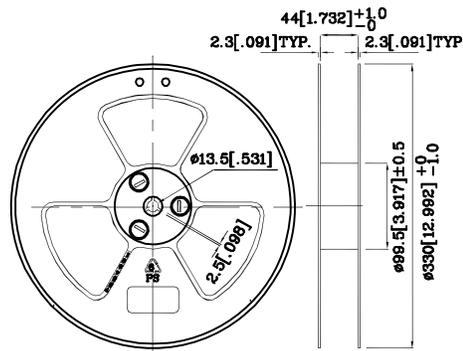
❖ Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.15)



❖ Tape Specification (Units : mm)



❖ Reel Dimension



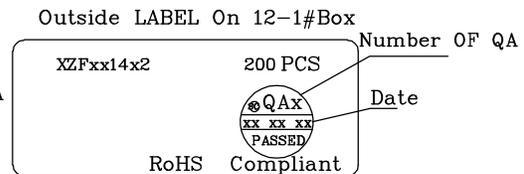
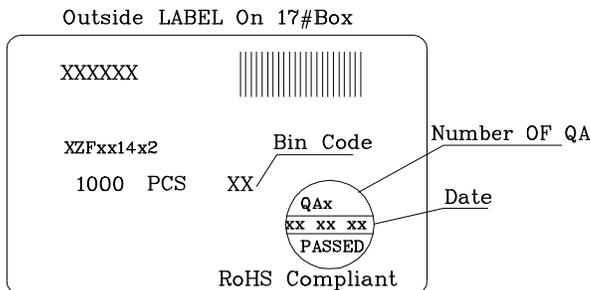
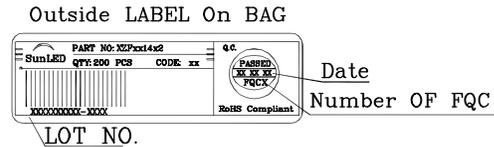
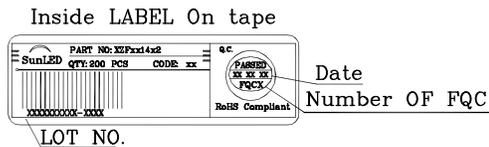
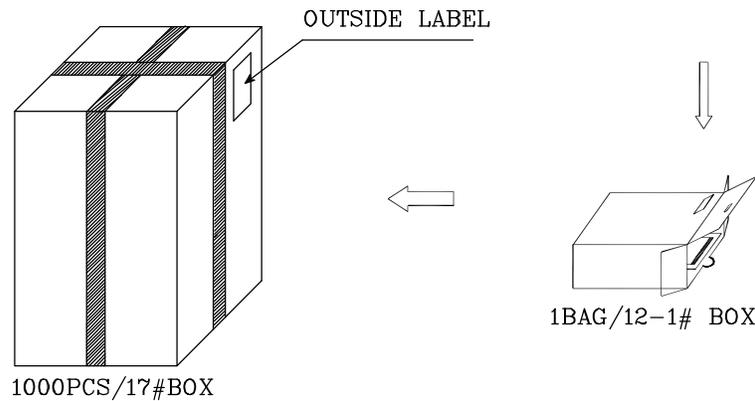
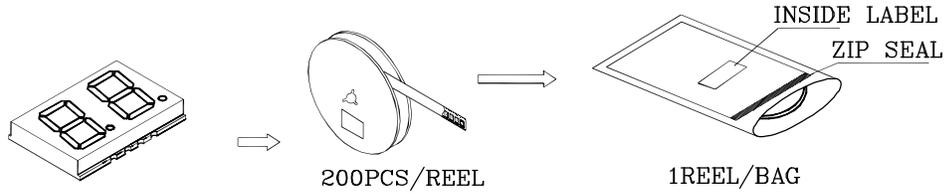
Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: ± 1 nm
2. Luminous intensity / luminous flux: $\pm 15\%$
3. Forward Voltage: ± 0.1 V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



TERMS OF USE

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2. Contents within this document are subject to improvement and enhancement changes without notice.
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